

PTO/SB/21 (08-00)

Approved for use through 10/31/2002. OMB 0651-0031 U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

## Under the Paper Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid AMB control number **Application Number** TRANSMITTAL 09/720,953 **FORM Filing Date** February 13, 2001 (to be used for all correspondence after initial filing) **First Named Inventor** Kiyotaka Tsukada Group Art Unit 2827 **Examiner Name** J. Norris Total Number of Pages in This Submission Attorney Docket Number 232.001 ENCLOSURES (check all that apply) After Allowance Communication **Assignment Papers** Fee Transmittal Form (for an Application) Appeal Communication to Board of Fee Attached Formal Drawings Appeals and Interferences Appeal Communication to Group Licensing-related Papers Amendment / Reply (Appeal Notice, Brief, Reply Brief) Petition **Proprietary Information** After Final Petition to Convert to a Status Letter Affidavits/declaration(s) Provisional Application Other Enclosure(s) (please Extension of Time Request Change of Correspondence identify below): Address Express Abandonment Request Return Postcard Terminal Disclaimer Information Disclosure Statement Request for Refund Certified Copy of Priority CD, Number of CD(s) Document(s) Response to Notification of Remarks Missing Requirements Under 35 USC 371 Response to Missing Parts under 37 CFR 1.52 or 1.53 SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT James F. Boyle, Reg. No. 33,653 Firm Boyle, Fredrickson, Newholm, Stein & Gratz, S.C. Individual name Signature Date 2002 CERTIFICATE OF MAILING I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class Nov. 1 mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231 on this date: Type or printed name Robyn O'Neill Date Signature

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## FEE TRANSMITTAL for FY 2002

Patent fees are subject to annual revision.

Applicant Claims small entity status. See 37 CFR 1.27

TOTAL AMOUNT OF PAYMENT

(\$)110.00

Complete if Known								
Application Number	09/720,953	151						
Filing Date	February 13, 2001	差之行						
First Named Inventor	Kiyotaka Tsukada	50 BY						
Examiner Name	J. Norris	902						
Group Art Unit	2827	JIM CELL						
Attorney Docket No.	232.001	Çi,						

METHOD OF PAYMENT (check all that apply)		FEE CALCULATION (continued)				0	
X Check Credit card Money Other None	eck Credit card Money Other None 3. ADDITIONA		NAL F	EES			
	Large	Entity	Small	Entity			
Deposit Account	Fee	Fee	Fee	Fee		Fee Paid	
Deposit Account 50-1170	105	130	205	65	Surcharge – late filing fee or oath		
Number Deposit Account Name  Boyle, Fredrickson, Newholm, Stein & Gratz S.C.		50	227	25	Surcharge – late provisional filing fee or cover sheet		
The Commissioner is authorized to: (check all that apply)		130	139	130	Non-English specification		
Charge fee(s) indicated below X Credit any overpayments		2.520	147	2.520	For filing a request for ex parte reexamination		
X Charge any additional fee(s) during the pendency of this application		920*	112	920*	Requesting publication of SIR prior to Examiner action		
Charge fee(s) indicated below, except for the filling fee to the above-identified deposit account.		1,840*	113	1,840*	Requesting publication of SIR after Examiner action		
FEE CALCULATION	115	110	215	55	Extension for reply within first month	110	
1. BASIC FILING FEE	116	400	216	200	Extension for reply within second month		
Large Entity   Small Entity	117	920	217	460	Extension for reply within third month		
Fee Fee Fee Fee Description Code (\$) Code (\$) Fee Paid	118	1,440	218	720	Extension for reply within fourth month		
101 740 201 370 Utility filing fee	128	1,960	228	980	Extension for reply within fifth month		
106 330 206 165 Design filing fee	119	320	219	160	Notice of Appeal		
107 510 207 255 Plant filing fee	120	320	220	160	Filing a brief in support of an appeal		
108 740 208 370 Reissue filing fee	121	280	221	140	Request for oral hearing		
114 160 214 80 Provisional filing fee	138	1,510	138	1,510	Petition to institute a public use proceeding		
		110	240	55	Petition to revive – unavoidable		
SUBTOTAL (1) (\$)0		1,280	241	640	Petition to revive – unintentional		
2. EXTRA CLAIM FEES FOR UTILITY AND REISSUE	142	1,280	242	640	Utility issue fee (or reissue)		
Extra Claims below Fee Paid	143	460	243	230	Design issue fee		
Total Claims -20**= X = Independent X = Independent	144	620	244	310	Plant issue fee		
Independent Claims - 3**= X = =	122	130	122	130	Petitions to the Commissioner		
Multiple Dependent =	123	50	123	50	Processing fee under 37 CFR 1.17(q)		
Large Entity Small Entity	126	180	126	180	Submission of Information Disclosure Stmt		
Fee Fee Fee Fee Description	581	40	581	40	Recording each patent assignment per property (times number of properties)		
103 18 203 9 Claims in excess of 20	146	740	246	370	Filing a submission after final rejection (37 CFR § 1.129(a))		
102 84 202 42 Independent claims in excess of 3	149	740	249	370	For each additional invention to be examined (37 CFR § 1.129(b))		
104 280 204 140 Multiple dependent claim, if not paid	179	740	279	370	Request for Continued Examination (RCE)		
109 84 209 42 **Reissue independent claims over original patent	169	169 900 169 900 Request for expedited examination of a design application					
110 18 210 9 **Reissue claims in excess of 20 and over original patent	110 18 210 9 **Reissue claims in excess of 20						
SUBTOTAL (2) (\$)0		fee (spe	cify)				
** or number previously paid, if greater; For Reissues, see above	*Reduc	ed by Bas	sic Filing	Fee Paid	SUBTOTAL (3) (\$)110.	00	

SUBMITTED BY	Complete (if applicable)				
Name (Print/Type)	James F. Boyle	Registration No. (Attorney/Agent)	33,653	Telephone	414-225-9755
Signature	イー FIM			Date	11-1-02

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THE UNITED STATES PATENT AND TRADEMARK OFFICE **CERTIFICATE OF MAILING** Application Of: I hereby certify that this correspondence is being KIYOTAKA TSUKADA ET AL deposited with the United States Postal Service as first class mail in an envelope addressed to: Serial No.: 09/720,953 ASSISTANT COMMISSIONER FOR PATENTS. Washington, D.C. 20231, this day of Filed: February 13, 2001 Group Art Unit: 2827 Rolling Dheill Examiner: J. Norris PRINTED CIRCUIT BOARD AND METHOD OF MANUFACTURING THE SAME)

## AMENDMENT

11/13/2002 JHCHILLA 00000005 501170

01 FC:1201

COMMISSIONER FOR PATENTS

Washington, D.C. 20231

Sir:

In response to the Office Action mailed July 5, 2002, a one-month extension of time being hereby requested with fee attached, please amend the above-identified application as follows:

Please cancel claims 1, 2, 4 and 10, and amend claims 3, 5, 9 and 11 as follows.

(Twice Amended) A method for manufacturing a printed circuit board comprising the 3. steps of:

coating a lower surface and an upper surface of an insulative substrate respectively with a lower surface metal foil and an upper surface metal foil, the thickness of which is less